

Title (en)
CONTACT ELEMENT FOR CONNECTING TO A CIRCUIT BOARD, CONTACT SYSTEM AND METHOD

Title (de)
KONTAKTELEMENT ZUM VERBINDEN MIT EINER LEITERPLATTE, KONTAKTSYSTEM UND VERFAHREN

Title (fr)
ÉLÉMENT DE CONTACT DESTINÉ À ÊTRE CONNECTÉ À UNE CARTE DE CIRCUITS IMPRIMÉS, SYSTÈME DE CONTACT ET PROCÉDÉ

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Abstract (en)
[origin: WO2014000920A1] The invention relates to a contact element for connecting to a circuit board. The circuit board has at least one substrate layer, particularly an electrically insulating substrate layer. The circuit board also has at least one electrically conductive layer. The contact element is designed for connecting to the electrically conductive layer. According to the invention, the contact element is designed to be pushed onto a circuit board edge of the circuit board. The contact element is designed to reach over the circuit board edge and has at least one cutting blade with a cutting edge, the cutting edge having a harder metal in the area of a severing section than in an adjoining contact section alongside the cutting edge. The cutting edge is designed to cut through the substrate layer with the severing section when pushed onto the circuit board edge and to contact the electrically conductive layer electrically with the contact section.

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